

### DESCRIPTION

STN456DN uses Trench MOSFET technology that is uniquely optimized to provide the most efficient high frequency switching performance. It has been optimized for low gate charge, low  $R_{DS(ON)}$  and fast switching speed.

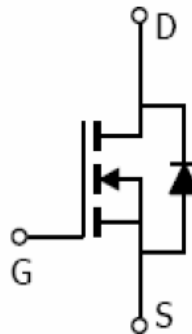
### PIN CONFIGURATION POWER PACK 5x6 (1212-8L)



**Y : Year Code**  
**A : Date Code**  
**B : Package Code**  
**C : Process Code**

### FEATURE

- 30V/30A,  $R_{DS(ON)} = 4.0m\Omega$  (Typ.)  
@ $V_{GS} = 10V$
- 30V/15A,  $R_{DS(ON)} = 5.8m\Omega$   
@ $V_{GS} = 4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- PPAK5x6 (1212-8L) package design





70A

**ABSOLUTE MAXIMUM RATINGS** (Ta = 25°C Unless otherwise noted )

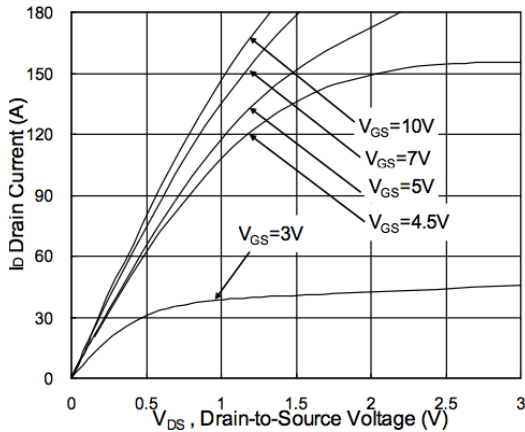
Parameter	Symbol	Typical	Unit
Drain-Source Voltage	VDSS	30	V
Gate-Source Voltage	VGSS	±20	V
Continuous Drain Current (TJ=150°C)	ID	TA=25°C 35	A
		TA=70°C 21	
Pulsed Drain Current	IDM	70	A
Continuous Source Current (Diode Conduction)	IS	90	A
Power Dissipation	PD	TA=25°C 74	W
Operation Junction Temperature	TJ	150	°C
Storage Temperature Range	TSTG	-55/150	°C
Thermal Resistance-Junction to Ambient	RθJA	62	°C/W



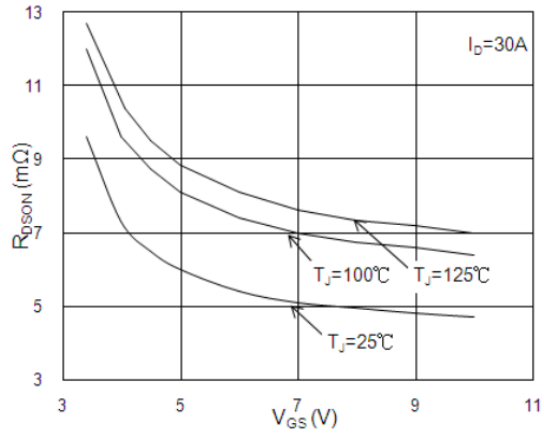
**ELECTRICAL CHARACTERISTICS** ( Ta = 25°C Unless otherwise noted )

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2		2.5	V
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=24V, V_{GS}=0V$			1	uA
		$V_{DS}=24V, V_{GS}=0V$ $T_J=55^\circ C$			5	
Drain-source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=30A$ $V_{GS}=4.5V, I_D=15A$		5.5 7.5	6.5 9.0	mΩ
Forward Transconductance	$g_{fs}$	$V_{DS}=5V, I_D=30A$		43		S
Diode Forward Voltage	$V_{SD}$	$I_S=1.0A, V_{GS}=0V$			1.0	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=15V, V_{GS}=4.5V$ $I_D=15A$		20		nC
Gate-Source Charge	$Q_{gs}$			7.6		
Gate-Drain Charge	$Q_{gd}$			7.2		
Input Capacitance	$C_{iss}$	$V_{DS}=15V, V_{GS}=0V$ $F=1MHz$		2295		pF
Output Capacitance	$C_{oss}$			267		
Reverse Transfer Capacitance	$C_{rss}$			210		
Turn-On Time	$t_{d(on)}$ $t_r$	$V_{DD}=15V, I_D=15A$ $V_{GS}=10V, R_G=3.3\Omega$		7.8		nS
Turn-Off Time	$t_{d(off)}$ $t_f$			15		
				37.3		
				1.6		

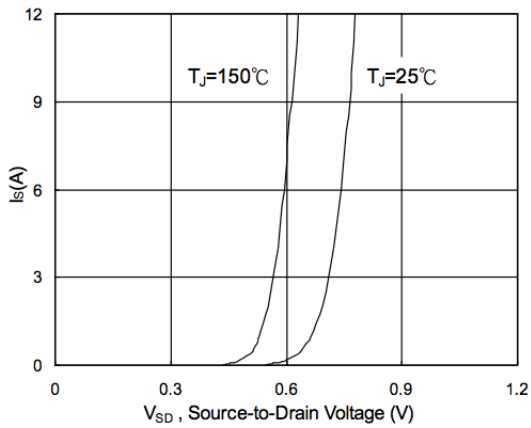
**TYPICAL CHARACTERISTICS** ( $T_j=25^\circ\text{C}$  unless otherwise noted)



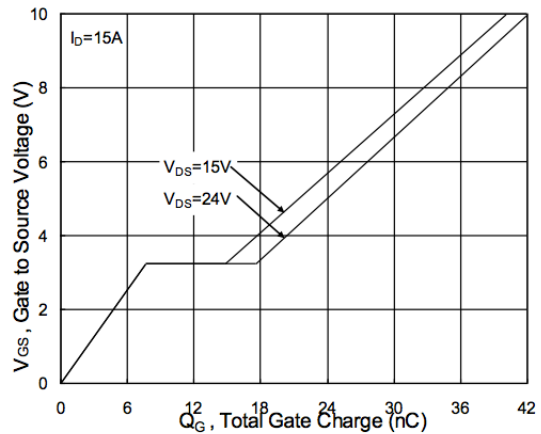
**Fig.1 Typical Output Characteristics**



**Fig.2 On-Resistance vs. G-S Voltage**

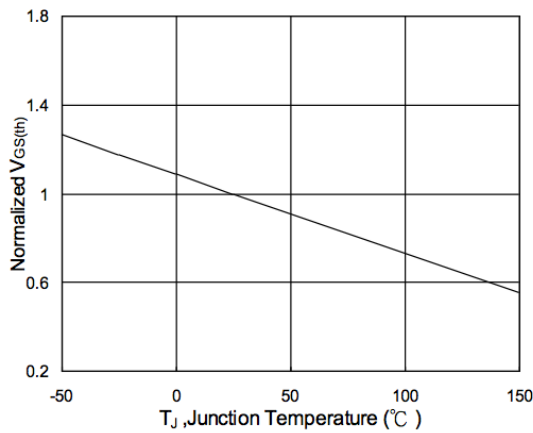


**Fig.3 Forward Characteristics of Reverse**

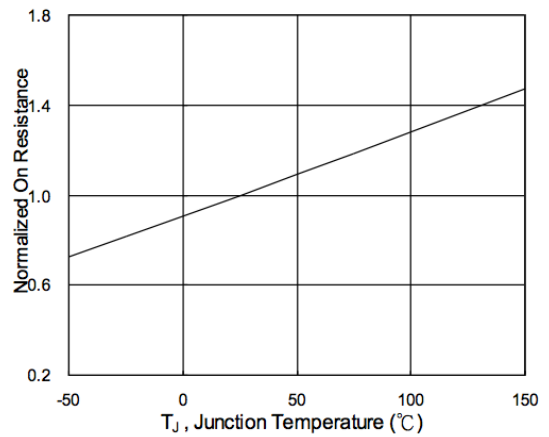


**Fig.4 Gate-Charge Characteristics**

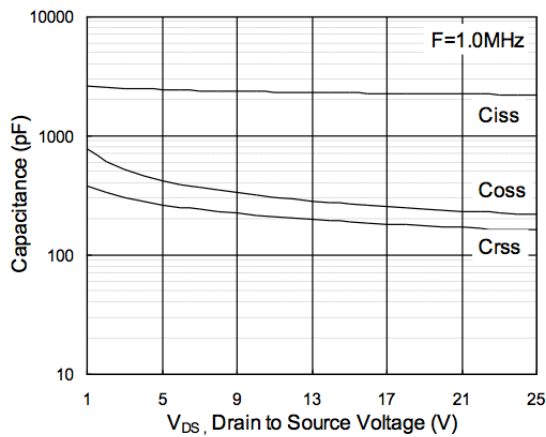
**TYPICAL CHARACTERISTICS (T<sub>J</sub>=25°C unless otherwise noted)**



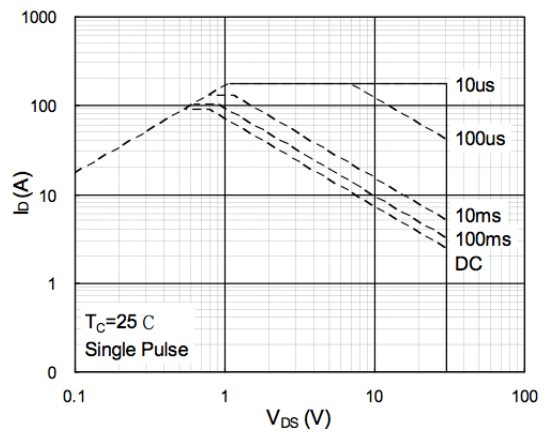
**Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>**



**Fig.6 Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>**

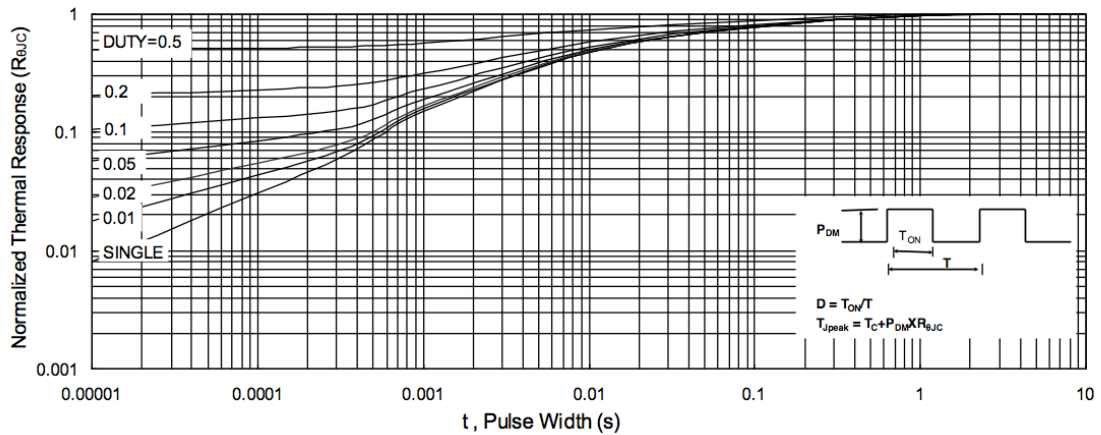


**Fig.7 Capacitance**

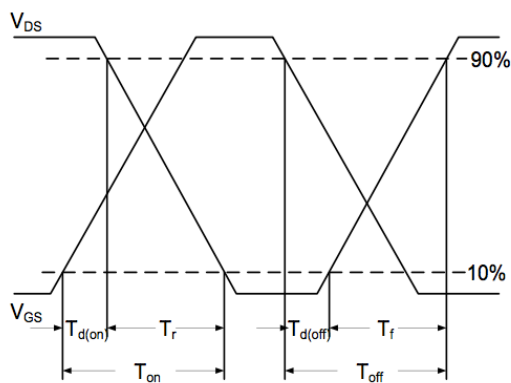


**Fig.8 Safe Operating Area**

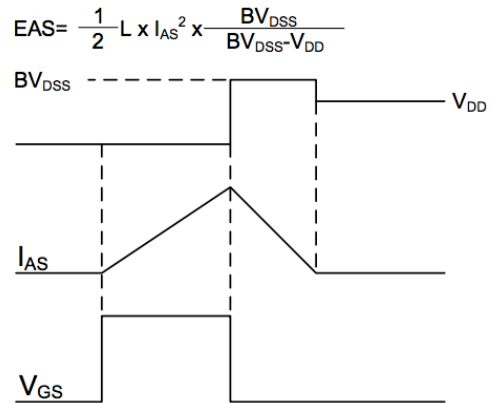
**TYPICAL CHARACTERISTICS** (T<sub>j</sub>=25°C unless otherwise noted)



**Fig.9 Normalized Maximum Transient Thermal Impedance**



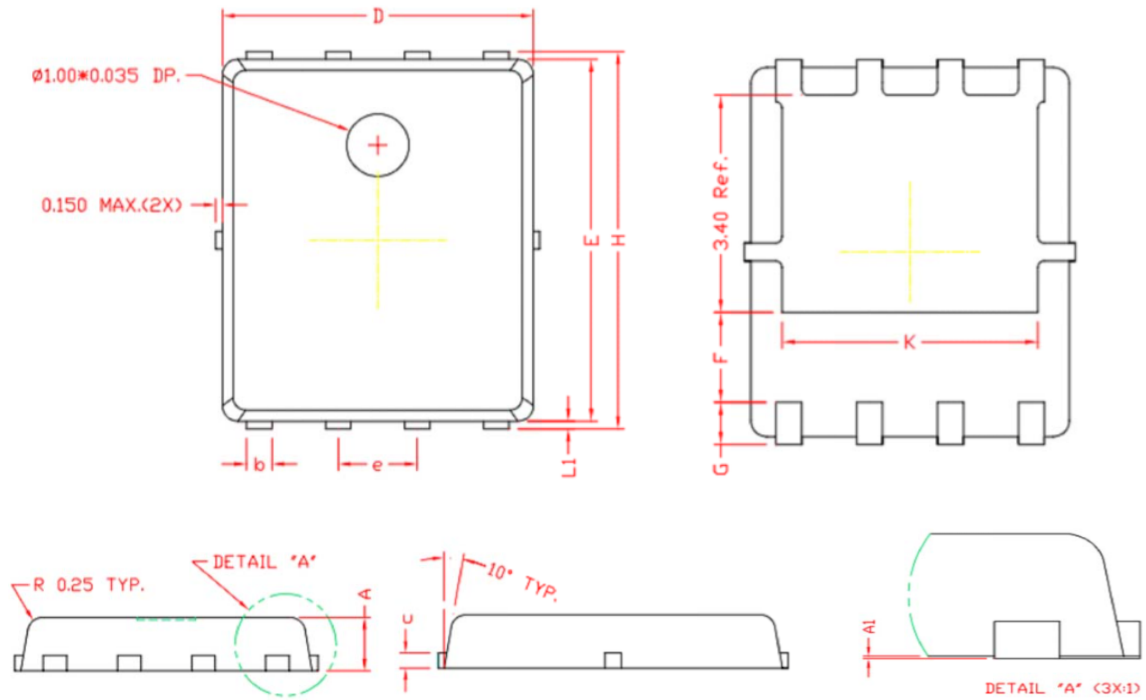
**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

**POWER PACKAGE 5x6 OUTLINE**



(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
b	0.35	0.42	0.49
c	0.254 REF.		
D	4.90	5.00	5.10
F	1.40 REF.		
E	5.70	5.80	5.90
e	1.27 BSC.		
H	5.95	6.08	6.20
L1	0.10	0.14	0.18
G	0.60 REF.		
K	4.00 REF.		